



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC0802NLS	Issued	23. June 2021
MA#	MA005432945		
Package	PG-TDSON-8-46	Weight*	119.27 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.457	1.22	1.22	12219	12219
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		317	
	non noble metal	copper	7440-50-8	37.762	31.67	31.71	316608	317020
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	375	375
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		715	
	plastics	epoxy resin	-	6.740	5.65		56511	
	inorganic material	silicondioxide	60676-86-0	35.833	30.04	35.76	300438	357664
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12171	12171
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1388	1388
solder	non noble metal	tin	7440-31-5	0.041	0.03		340	
	noble metal	silver	7440-22-4	0.051	0.04		425	
	non noble metal	lead	7439-92-1	1.934	1.62	1.69	16216	16981
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		187	
	non noble metal	copper	7440-50-8	22.292	18.69	18.72	186903	187146
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			29	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.49	9.50	94912	95036
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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